

DUAL DIGIT SMD DISPLAY (0.56")



LSDD515/6WK-XX/T
DATA SHEET

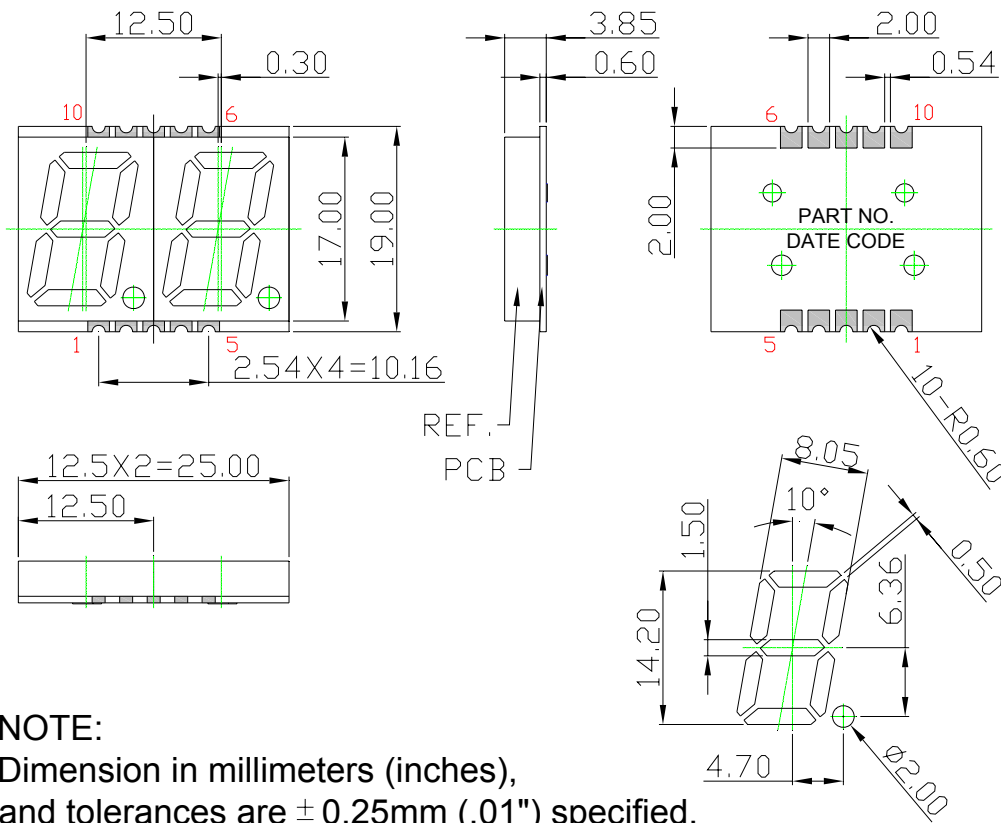
DOC.NO : QW0905-LSDD515/6WK-XX/T

REV. : A

DATE : 07 – Jan. – 2015

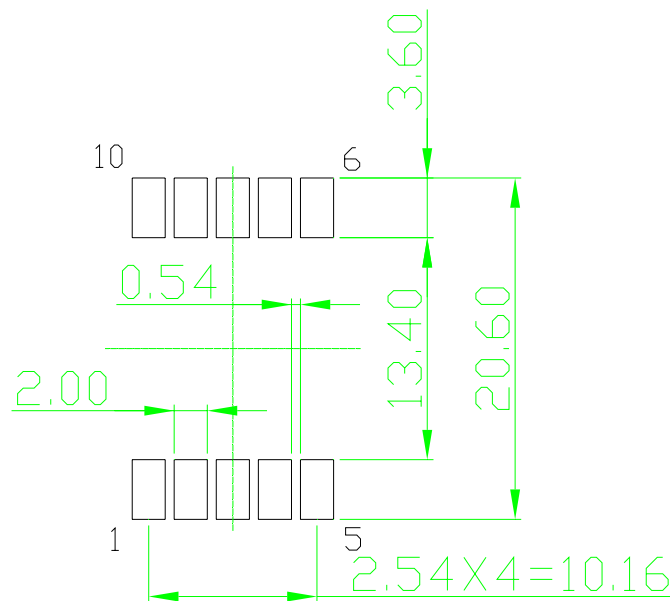


Package Dimensions

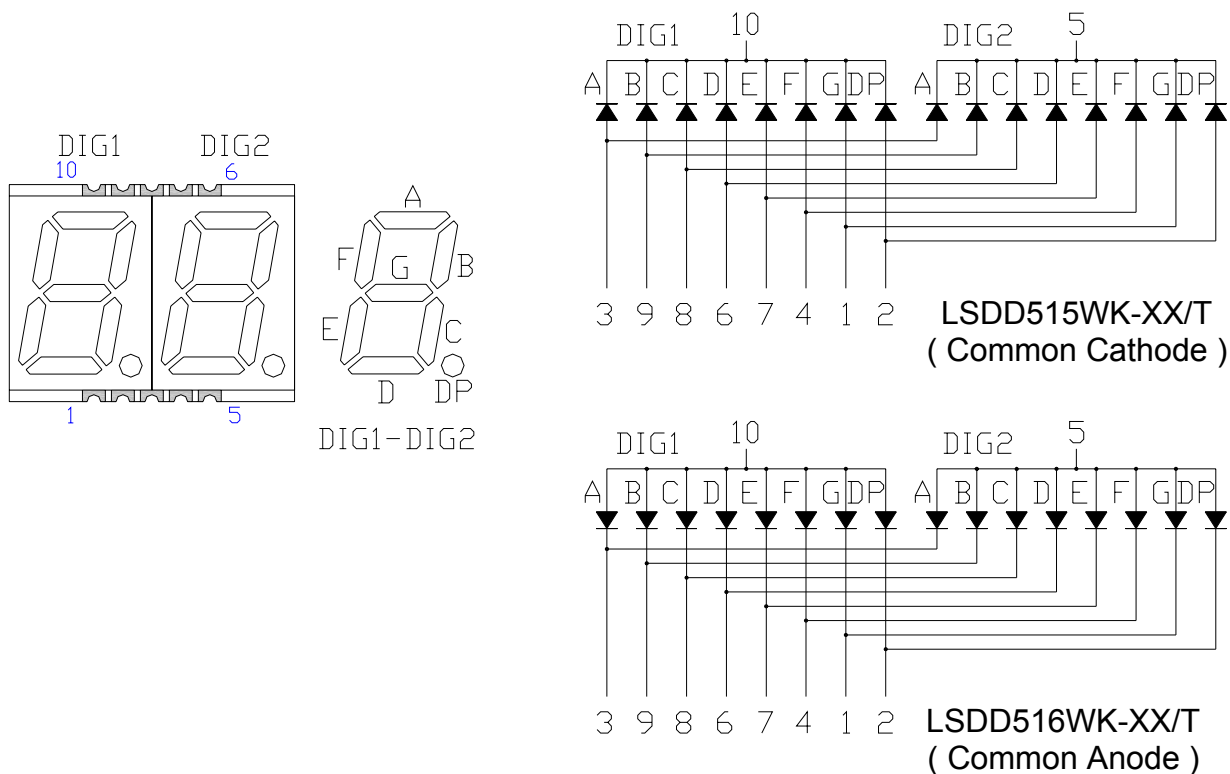


NOTE:
Dimension in millimeters (inches),
and tolerances are $\pm 0.25\text{mm}$ (.01") specified.

Recommended Soldering Pad Dimensions



Internal Circuit Diagram



Electrical Connection

PIN NO.	LSDD515WK-XX/T	PIN NO.	LSDD516WK-XX/T
1	Anode G	1	Cathode G
2	Anode DP	2	Cathode DP
3	Anode A	3	Cathode A
4	Anode F	4	Cathode F
5	Common Cathode DIG2	5	Common Anode DIG2
6	Anode D	6	Cathode D
7	Anode E	7	Cathode E
8	Anode C	8	Cathode C
9	Anode B	9	Cathode B
10	Common Cathode DIG1	10	Common Anode DIG1

Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Ratings	UNIT
Power Dissipation	PD	64	mW
Peak pulse current Duty 1/10@10KHz	I _{FP}	80	mA
Forward Current Per Chip	I _F	20	mA
Storage Temperature	T _{stg}	-40 ~ +90	°C
Operating Temperature	T _{opr}	-30 ~ +85	°C

Typical Electrical & Optical Characteristics (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Luminous Intensity	IV	---	30	----	mcd	IF=5mA
Chromaticity Coordinates	X	----	0.29	----	----	IF=5mA
	Y	----	0.28	----	----	IF=5mA
Forward Voltage	VF	2.5	----	3.5	V	IF=5mA
Reverse Current	I _r	----	----	10	μA	VR=5V

Note : 1.The forward voltage data did not including ±0.1V testing tolerance.

2.The luminous intensity data did not including ±15% testing tolerance.

Typical Electro-Optical Characteristics Curve

(25 °C Free Air Temperature Unless Otherwise Specified)

WK: Super Bright white (InGaN/GaN) CURVE

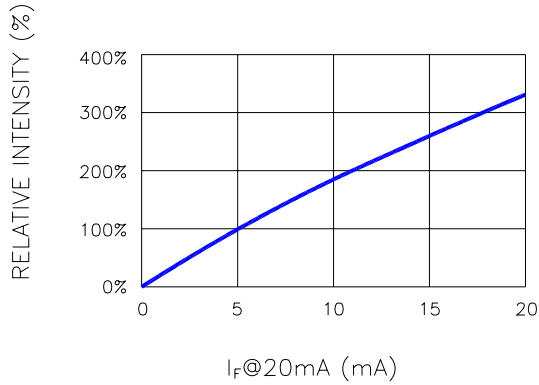


Fig.1 RELATIVE INTENSITY VS. FORWARD CURRENT

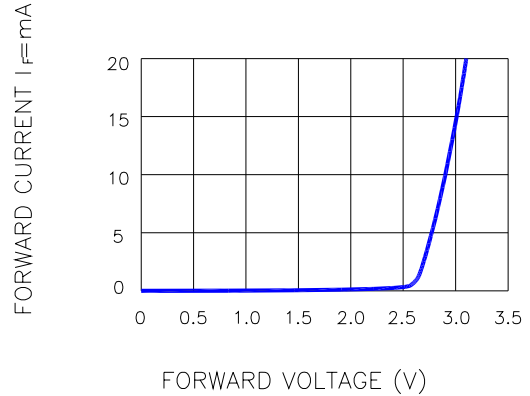


Fig.2 FORWARD CURRENT VS. FORWARD VOLTAGE

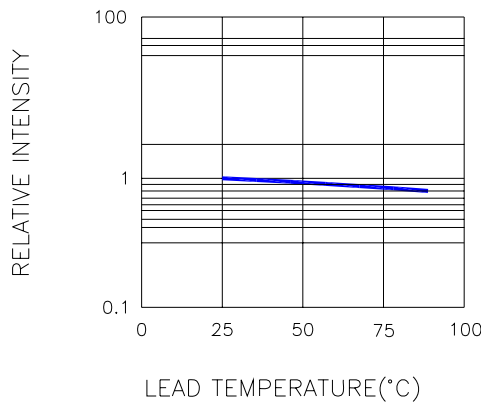


Fig.3 RELATIVE INTENSITY VS. LEAD TEMPERATURE
(PULSED 20 mA; 300us PULSE, 10ms PERIOD)

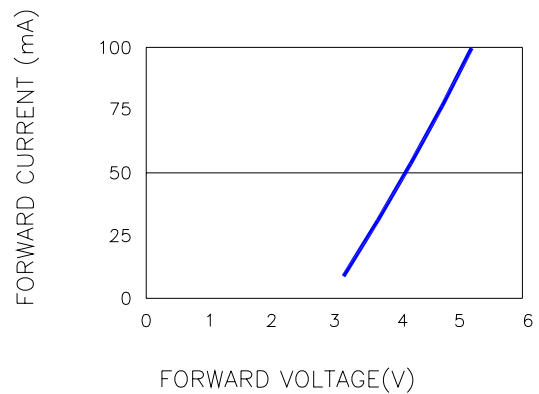


Fig.4 PEAK FORWARD VOLTAGE VS. FORWARD (100us TEST PULSE, 1% DUTY CYCLE)

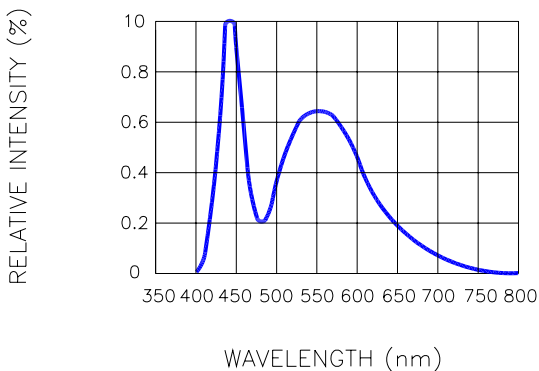


Fig.4 RELATIVE INTENSITY VS. WAVELENGTH

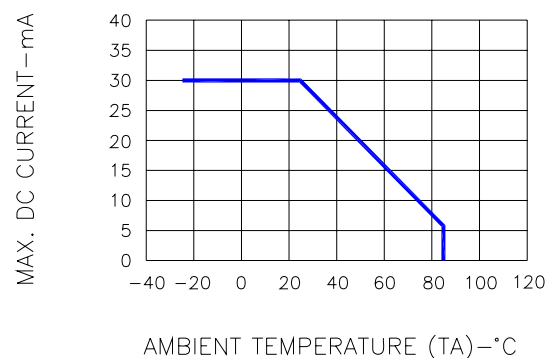
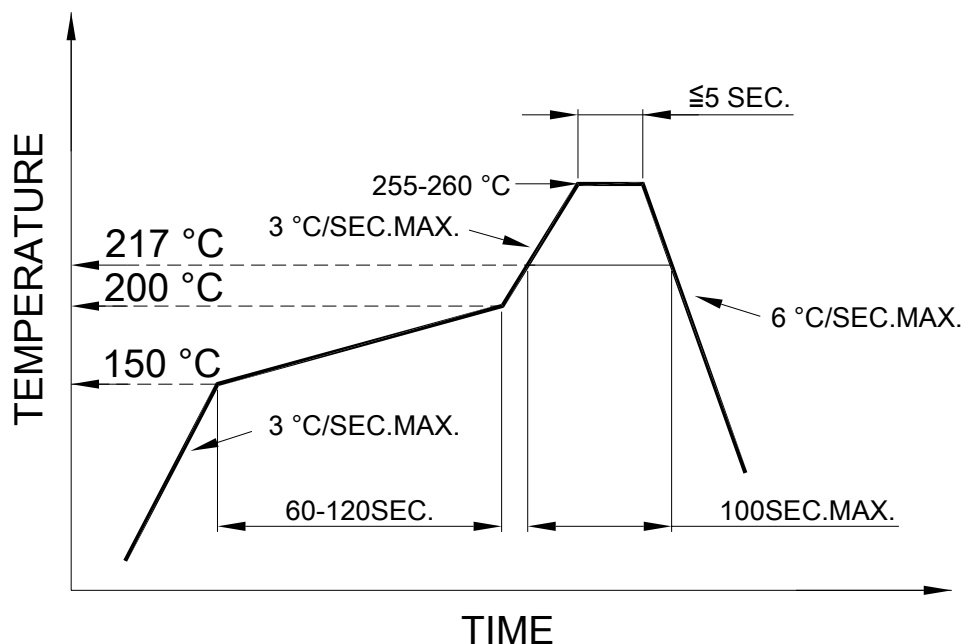


Fig.7 MAX. ALLOWABLE DC CURRENT VS. AMBIENT TEMPERATURE

SMT REFLOW SOLDERING INSTRUCTIONS

SMT Soldering Profile

Pb free reflow soldering Profile



SOLDERING IRON

Basic spec is ≤ 4 sec when 260°C. If temperature is higher, time should be shorter (+10°C→1 sec). Power dissipation of Iron should be smaller than 15W, and temperature should be controllable. Surface temperature of the device should be under 230°C.

REWORK

Customer must finish rework within 3 sec. under 350°C.

The head of soldering iron cannot touch copper foil.